### Overview

HP ProBook x360 11 G5 EE



- 1. Webcam LED
- 2. 720p Webcam or optional HP Privacy Camera
- 3. Microphone
- 4. ClickPad
- 5. World-facing 5 Megapixels Webcam (Optional)

#### Left

- 6. World-facing Webcam LED (Optional)
- 7. Power Button
- 8. Headphone / Microphone Combo Jack
- 9. USB 3.1 Gen 1 Port
- 10. Security Lock Slot (Nano lock sold seperately)



### Overview



- 1. Power Connector
- 2. Ethernet (RJ-45) Port
- 3. HDMI Port (Cable not included)

#### Right

- 4. USB 3.1 Gen 1 Port
- 5. USB Type-C<sup>™</sup> (Data and Power in-out)



### Overview

### AT A GLANCE

- Starting at 3.16 lbs (1.44 kg) touch
- At 21 mm (0.83"), this flexible 360° hinge converts to laptop, tablet, tent, stand or book mode easily
- Designed to pass MIL-STD 810G testing<sup>1</sup> with rugged features such as co-molded rubber trim, spill- and pick-resistant keyboard, and Corning<sup>®</sup> Gorilla<sup>®</sup> Glass 3 touch screen
- Optional dual camera system for project-based learning
- New optional active HP Pro Pen is engineered for the classroom durable tips require less replacing
- Pre-installed with Windows 10 Pro 64, Windows 10 Pro 64 (National Academic), Windows 10 Home 64, or Windows 10 Pro in S mode 64, FreeDOS<sup>2</sup>
- Powered by Intel<sup>®</sup> Celeron<sup>®</sup> N4000, Intel<sup>®</sup> Celeron<sup>®</sup> N4100 and Intel<sup>®</sup> Pentium<sup>®</sup> N4020, N4120 and Pentium N5000, N5030 processors
- Choice of 29.4cm (11.6") diagonal HD UWVA slim LED touch screen (1366 x 768) or 29.4 cm (11.6") diagonal HD SVA slim LED touch screen (1366 x 768) displays
- 64 GB eMMC, 128 GB SATA-3 TLC Solid State Drive or up to 256 GB SATA-3 Solid State Drive storage options
- Up to 8 GB system memory for enhanced memory management
- Reliable connectivity with choice of Intel<sup>®</sup> Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) WiFi and Bluetooth<sup>®</sup> 5.0 Combo WLAN or Intel<sup>®</sup> Dual Band Wireless-AX200 802.11a/b/g/n/ax (2x2) Wi-Fi 6 and Bluetooth<sup>®</sup> 5.0 Combo WLAN for learning and collaboration beyond the classroom
- Built-in ports include: Ethernet (RJ-45), 2 USB 3.1 Gen 1, USB Type-C<sup>™</sup>, and HDMI 1.4b port for connecting to high-resolution displays
- Enhanced security TPM 2.0 discrete chip
- Battery life Up to 16 hours and 45 minutes<sup>3</sup>

1. MIL STD 810H testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

2. FreeDOS planned to be available March 2020.

3. Recharges the battery up to 90% within 90 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

#### NOTE: See important legal disclosures for all listed specs in their respective features sections.



### **Technical Specifications**

### **PRODUCT NAME**

HP ProBook x360 11 G5 EE

### **OPERATING SYSTEM**

Preinstalled

Windows 10 Pro 64<sup>1</sup> Windows 10 Pro 64 (National Academic only)<sup>2</sup> Windows® 10 Home 64<sup>1</sup> Windows 10 Home Single Language 64<sup>1</sup> Windows 10 Pro in S mode 64<sup>3</sup> Windows 10 Pro in S mode 64 (National Academic only)<sup>2,3</sup> Windows 10 Pro (Windows 10 Enterprise available with a Volume Licensing Agreement)<sup>1</sup>

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

3. Windows 10 Pro in S mode 64 works exclusively with apps from the Windows store. Some accessories and apps compatible with Windows 10 may not work, and performance may vary. Certain default settings, features, and apps cannot be changed. Easily switch to Windows 10 Pro configuration (fee applies) Learn more at Microsoft.com/Windows 10S.

### PROCESSORS

Intel<sup>®</sup> Pentium<sup>®</sup> Silver N5000 with Intel<sup>®</sup> UHD Graphics 605 (1.1 GHz base frequency, up to 2.7 GHz burst frequency, 4 MB cache, 4 cores)<sup>4,5,6</sup>

Intel<sup>®</sup> Celeron<sup>®</sup> N4100 with Intel<sup>®</sup> UHD Graphics 600 (1.1 GHz base frequency, up to 2.4 GHz burst frequency, 4 MB cache, 4 cores)<sup>4,5,6</sup>

Intel<sup>®</sup> Celeron<sup>®</sup> N4000 with Intel<sup>®</sup> UHD Graphics 600 (1.1 GHz base frequency, up to 2.6 GHz burst frequency, 4 MB cache, 2 cores)<sup>4,5,6</sup>

Intel<sup>®</sup> Pentium<sup>®</sup> Silver N5030 with Intel<sup>®</sup> UHD Graphics 605 (1.1 GHz base frequency, up to 3.1 GHz burst frequency, 4 MB cache, 4 cores)<sup>4,5,6</sup>

Intel<sup>®</sup> Celeron<sup>®</sup> N4020 with Intel<sup>®</sup> UHD Graphics 600 (1.1 GHz base frequency, up to 2.8 GHz burst frequency, 4 MB cache, 2 cores)<sup>4,5,6</sup>

Intel<sup>®</sup> Celeron<sup>®</sup> N4120 with Intel<sup>®</sup> UHD Graphics 600 (1.1 GHz base frequency, up to 2.6 GHz burst frequency, 4 MB cache, 4 cores)<sup>4,5,6</sup>

#### **Processors Family**

Intel<sup>®</sup> Celeron<sup>®</sup> processor (N4000, N4020, 4120)<sup>6</sup> Intel<sup>®</sup> Pentium<sup>®</sup> Silver processor (N5000, N5030)<sup>6</sup>

4. Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload



## **Technical Specifications**

and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

5. Processor speed denotes maximum performance mode; processors will run at lower speeds in battery optimization mode.
 6. In accordance with Microsoft's support policy, HP does not support the Windows 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows 8 or Windows 7 drivers on http://www.support.hp.com.

### CHIPSET

Chipset is integrated with processor

### GRAPHICS

#### Integrated

Intel<sup>®</sup> UHD Graphics 605 (for Pentium Silver)<sup>7</sup> Intel<sup>®</sup> UHD Graphics 600 (for Celeron)<sup>7</sup>

7. HD content required to view HD images

### DISPLAY

Internal Non Touch 29.46 cm (11.6") diagonal HD SVA eDP WLED-backlit with HD camera, 220 nits, 45% NTSC (1366 x 768)<sup>7,8,9</sup>

#### Touch

29.46 cm (11.6") diagonal HD SVA eDP WLED-backlit touch screen with HD camera, 220 nits, 45% NTSC (1366 x 768)<sup>7,8,9</sup> 29.46 cm (11.6") diagonal HD IPS eDP WLED-backlit touch screen with HD camera, 220 nits, 50% NTSC (1366 x 768)<sup>7,8,9</sup>

#### HDMI

Port supports resolutions up to 3840 x 2160 external resolution @30 Hz

7. HD content required to view HD images.

8. Resolutions are dependent upon monitor capability, and resolution and color depth settings.

9. Sold separately or as an optional feature.



### **Technical Specifications**

### **STORAGE AND DRIVES**

#### Primary Storage M.2

128 GB SATA-3 TLC Solid State Drive<sup>10,11</sup> 256 GB SATA-3 TLC Solid State Drive<sup>10,11</sup>

#### eMMC Configurations

64 GB eMMC<sup>10</sup>

10. For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 30 GB (for Windows 10) is reserved for system recovery software.
11. Not available with eMMC storage.

#### MEMORY

Standard Maximum Memory 8 GB DDR4-2400 SDRAM<sup>12</sup>

#### Memory

4 GB DDR4-2400 SDRAM (on-board)<sup>12</sup> 8 GB DDR4-2400 SDRAM (on-board)<sup>12</sup>

12. Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

### **NETWORKING/COMMUNICATIONS**

#### WLAN

Intel<sup>®</sup> Dual Band Wireless-AC 9560 802.11a/b/g/n/ac (2x2) Wi-Fi<sup>®</sup> and Bluetooth<sup>®</sup> 5 Combo, non-vPro<sup>™13</sup> Intel<sup>®</sup> Dual Band Wireless-AX200 802.11a/b/g/n/ax (2x2) Wi-Fi 6 and Bluetooth<sup>®</sup> 5 Combo, non-vPro<sup>™</sup> \* Realtek Dual Band Wireless- 8852AE 802.11ax (2x2) Wi-Fi 6 and Bluetooth<sup>®</sup> 5.2 Combo, non-vPro<sup>™13</sup>

Miracast

Native Miracast Support<sup>14</sup>

#### Ethernet

Realtek RTL8111HSH-CG 10/100/1000 GbE NIC<sup>15</sup>

13. Wireless access point and Internet service required and sold separately. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.
 14. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming.
 15. The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server



### **Technical Specifications**

#### and network infrastructure is required.

\*Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 6 is backwards compatible with prior 802.11 specs. The specifications for Wi-Fi 6 (802.11ax) are draft and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ax devices.

### AUDIO/MULTIMEDIA

Audio HP HD Audio 2 Integrated stereo speakers

**Speaker Power** 2W/20hm per speaker

**Camera** User-facing 720p HD camera<sup>7,16</sup> Located on display

Webcam

World-facing 5 MP secondary camera (Optional)<sup>7,9,16</sup>

7. HD content required to view HD images.

- 9. Sold separately or as an optional feature.
- 16. Internet access required.

### **KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS/PEN**

#### Keyboard

Full-sized chiclet keyboard, pick proof

#### **Pointing Device**

Clickpad with multi-touch gesture support, taps enabled as default Default on: 2-finger scroll, pinch Support Windows 10 modern Trackpad gestures

#### **Function Keys**

- F1 Blank
- F2 Blank
- F3 Sleep
- F4 Display Switching
- F5 Audio Mute/Unmute
- F6 Volume <down>
- F7 Volume <up>
- F8 Mic Mute/Unmute
- F9 Brightness <down>



### **Technical Specifications**

F10 - Brightness <up> F11 - Blank F12 - Wireless On/Off

#### Pen

Optional Passive Targus Slim Stylus\* Optional Active HP Pro Pen

Sensors Combo Chip Accelerometer Magnetometer Gyroscope Hall Sensor

\*Optional Passive Targus Slim Stylus

### SOFTWARE AND SECURITY

#### BIOS

HP BIOSphere Gen5<sup>17</sup> HP Drive Lock & Automatic Drive Lock<sup>18</sup> BIOS Update via Network Master Boot Record Security Power On Authentication Secure Erase<sup>19</sup> Absolute Persistence Module<sup>20</sup> Pre-boot Authentication

#### Software

HP Connection Optimizer HP School Pack HP Interactive Light HP Image Assistant HP Hotkey Support HP JumpStart HP Support Assistant<sup>21</sup> HP Noise Cancellation Software Buy Office (sold separately)

#### **Manageability Features**

HP Driver Packs<sup>22</sup> HP System Software Manager (SSM) HP BIOS Config Utility (BCU) HP Client Catalog HP Manageability Integration Kit Gen3<sup>23</sup>



### **Technical Specifications**

#### **Client Security Software**

HP Client Security Manager Gen5<sup>24</sup> Windows Defender<sup>25</sup>

#### **Security Management**

Pre-boot Authentication TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)<sup>26</sup> USB enable/disable (via BIOS) Power-on password (via BIOS) Setup password (via BIOS) Support for chassis padlocks and cable lock devices HP Sure Click<sup>27</sup>

17. HP BIOSphere Gen5 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

18. HP Drive Lock & Automatic Drive Lock is not supported on NVMe drives

 19. For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane™.
 20. Absolute firmware module is shipped turned off and can only be activated with the purchase a license subscription and full activation of the software agent. License subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. Certain

conditions apply. For full details visit: https://www.absolute.com/about/legal/agreements/absolute/.

21. HP Support Assistant requires Windows and Internet access.

22. HP Driver Packs not preinstalled, however available for download at

http://www.hp.com/go/clientmanagement.

23. HP Manageability Integration Kit can be downloaded from http://www.hp.com/go/clientmanagement.
24. HP Client Security Manager Gen5 requires Windows and is available on the select HP Pro and Elite PCs. See product specifications for details.

25. Windows Defender Opt in and internet connection required for updates.

26. Firmware TPM is version 2.0. Hardware TPM is v1.2, which is a subset of the TPM 2.0 specification version v0.89 as implemented by Intel Platform Trust Technology (PTT).

27. HP Sure Click is available on select HP platforms and supports Microsoft<sup>®</sup> Internet Explorer, Google Chrome, and Chromium<sup>™</sup>. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become available.



### **Technical Specifications**

#### POWER

#### **Power Supply**

HP Smart 45 W External AC power adapter<sup>28</sup> HP Smart 65 W EM External AC power adapter<sup>28</sup> HP Smart 45 W USB Type-C<sup>™</sup> adapter<sup>28</sup>

#### **Primary Battery**

HP Long Life 3-cell, 48 Wh Li-ion (90% in 90 minutes)<sup>29,30</sup>

**Power Cord** 3-wire plug - 1m

**Battery life** Up to 16 hours and 45 minutes<sup>31</sup>

#### 28. Availability may vary by country.

29. Battery is internal and not replaceable by customer. Serviceable by warranty.

30. Windows 10 MM14 battery life will vary depending on various factors including product model, configuration, loaded applications, features, use, wireless functionality, and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See http://www.bapco.com for additional details.

31. Recharges the battery up to 90% within 90 minutes when the system is off or in standby mode. Power adapter with a minimum capacity of 65 watts is required. After charging has reached 50% capacity, charging will return to normal. Charging time may vary +/-10% due to System tolerance.

#### **WEIGHTS & DIMENSIONS**

**Product Weight** Starting at 3.16 lb<sup>32</sup> Starting at 1.44 kg<sup>32</sup>

**Product Dimensions (w x d x h)** 11.8 x 8.8 x 0.83 in 30 x 20.53 x 2.12 cm

32. Weight will vary by configuration.

### **PORTS/SLOTS**

#### Ports

2 USB 3.1 Gen 1 1 USB Type-C<sup>™</sup> (Data transfer, power delivery) 1 HDMI 1.4b<sup>33</sup> 1 AC power 1 RJ-45



### **Technical Specifications**

1 headphone/microphone combo jack

33. HDMI cable sold separately.

### SERVICE AND SUPPORT

HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.<sup>34</sup>

34. HP Services offers 1-year limited warranties and 90 day software limited warranty options depending on country. Batteries have a default one year limited warranty refer to http://www.hp.com/support/batterywarranty/ for additional battery information. On-site service and extended coverage is also available. HP Care Pack Services are optional extended service contracts that go beyond the standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/cpc.



## **Technical Specifications**

### **ENVIRONMENTAL & INDUSTRY**

Environmental	<b>Eco-Label Certifications</b>	This product has received or is in the process of being certified to the following				
Data	& declarations	approvals and may be labeled with one or more of these marks:				
		• IT ECO declaration				
		• US ENERGY STAR®				
		<ul> <li>EPEAT<sup>®</sup> Silver registered in the United States. See <a href="http://www.epeat.net">http://www.epeat.net</a> for registration status in your country.</li> <li>TCO Certified 8.0</li> </ul>				
	System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions				
		data for the Notebook model is based on a "Typically Configured Notebook".				
	Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
		2.50.11		0.50 W		
	Normal Operation	3.50 W	3.58 W	3.52 W		
	(Sort idle)					
	Normal Operation	1.30 W	1.26 W	1.30 W		
	(Long idle)					
	Sleep	0.29 W	0.31 W	0.29 W		
	Off	0.24 W	0.26 W	0.24 W		
		Energy efficiency data listed is for an ENERGY STAR <sup>®</sup> compliant product if offered within the model family. HP computers marked with the ENERGY STAR <sup>®</sup> Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR <sup>®</sup> specifications for computers. If a model family does not offer ENERGY STAR <sup>®</sup> compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows <sup>®</sup> operating system.				
	Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz		
	Normal Operation (Short idle)	12 BTU/hr	12 BTU/hr	12 BTU/hr		
	Normal Operation (Long idle)	4 BTU/hr	4 BTU/hr	4 BTU/hr		
	Sleep	1 BTU/hr	1 BTU/hr	1 BTU/hr		
	Off	1 BTU/hr	1 BTU/hr	1 BTU/hr		



	*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.	
Declared Noise	Sound Power	Sound Pressure
Emissions	(L <sub>WAd</sub> , bels)	(L <sub>pAm</sub> , decibels)
(in accordance with ISO 7779 and ISO 9296)		
Typically Configured – Idle	2.5	15
Fixed Disk – Random writes	2.5	14
Longevity and Upgrading	Longevity and Upgrading       This product can be upgraded, possibly extending its useful life by several Upgradeable features and/or components contained in the product may in 3 USB ports         • 3 USB ports       • 1 PC card slot (type I/II)         • 1 ExpressCard/54 slot       • 1 IEEE 1394 Port         • Optional expansion base docking station       • 1 multi-bay II storage port         • Interchangeable HDD       Spare parts are available throughout the warranty period and or for up to years after the end of production.         Batteries       This battery(s) in this product comply with EU Directive 2006/66/EC         Batteries used in the product do not contain:         Mercury greater than 20ppm by weight         Cadmium greater than 20ppm by weight         Battery size: CR2032 (coin cell)         Battery type: Lithium	
Batteries		



Additional Information	• 7 • 7 • 7 • 7 • 7 • 7 • 7 • 7	<ul> <li>This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.</li> <li>This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive - 2002/96/EC.</li> <li>This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).</li> <li>This product is in compliance with the IEEE 1680.1 (EPEAT) standard at the <silver> level, see www.epeat.net</silver></li> <li>Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.</li> <li>This product is 96.1% recycle-able when properly disposed of at end of life.</li> </ul>	
Packaging Materials	erials External:	PAPER/Corrugated	235 g
	Internal:	PLASTIC/Polypropylene - PP	3 g
		PLASTIC/Polyethylene Expanded - EPE	27 g
		PLASTIC/Polyethylene low density - LDPE	13 g
	http://ww Asbesto Certain Certain plastics Cadmiuu Chlorina Chlorina Formalo Haloger Lead can Nercurio Nickel – frequentl Ozone D Polybro Polybro Polycho Polycho	This product does not contain any of the following substances in excess of         regulatory limits (refer to the HP General Specification for the Environment at         http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):         • Asbestos         • Certain Azo Colorants         • Certain Brominated Flame Retardants – may not be used as flame retardants in         plastics         • Cadmium         • Chlorinated Hydrocarbons         • Chlorinated Paraffins         • Formaldehyde         • Halogenated Diphenyl Methanes         • Lead and Lead compounds         • Mercuric Oxide Batteries         • Nickel – finishes must not be used on the external surface designed to be         frequently handled or carried by the user.         • Ozone Depleting Substances         • Polybrominated Biphenyls (PBBs)         • Polybrominated Biphenyl Oxides (PBBCs)         • Polybrominated Biphenyl (PCB)         • Polychlorinated Terphenyls (PCT)         • Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail         packaging has been voluntarily removed from most applications.	



		Radioactive Substances
		• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
6	Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
		<ul> <li>Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.</li> </ul>
		• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
		<ul> <li>Design packaging materials for ease of disassembly.</li> </ul>
		<ul> <li>Maximize the use of post-consumer recycled content materials in packaging materials.</li> </ul>
		<ul> <li>Use readily recyclable packaging materials such as paper and corrugated materials.</li> </ul>
		<ul> <li>Reduce size and weight of packages to improve transportation fuel efficiency.</li> <li>Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.</li> </ul>
	End-of-life Management	HP Inc. offers end-of-life HP product return and recycling programs in many
a	and Recycling	geographic areas. To recycle your product, please go to:
		http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
		The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
	HP, Inc. Corporate	For more information about HP's commitment to the environment:
	Environmental	Global Citizenship Report
	nformation	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
		Eco-label certifications
		http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
		ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product _Design_ISO_14K_Certificate.pdf
		and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



SYSTEM UNIT	
Stand-Alone Power Requirements (AC Power)	
Nominal Operating Voltage	19V
Average Operating Power	Win 10
Integrated graphics	Yes
Max Operating Power	UMA<45W
Temperature	
Operating	32° to 95° F (0° to 35° C)
Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	
Operating	10% to 90%, non-condensing
Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	
Operating	40 G, 2 ms, half-sine
Non-operating	240 G, 2 ms, half-sine
Random Vibration	
Operating	0.75 grms
Non-operating	1.50 grms
Altitude (unpressurized)	
Operating	-50 to 10,000 ft (-15.24 to 3,048 m)
Non-operating	-50 to 40,000 ft (-15.24 to 12,192 m)
Planned Industry Standard	
Certifications	
UL	Yes
CSA	Yes
FCC Compliance	Yes
ENERGY STAR®	Yes <sup>36</sup>
EPEAT <sup>®</sup> 2019	Yes, Silver in U.S. <sup>37</sup>
ICES	Yes
Australia	Yes
NZ A-Tick Compliance	Yes
CCC	Yes
Japan VCCI Compliance	Yes
KC	Yes
BSMI	Yes
CE Marking Compliance	Yes
BNCI or BELUS	Yes
CIT	Yes
GOST	Yes



## **Technical Specifications**

Saudi Arabian Compliance (ICCP)	Yes
SABS	Yes
UKRSERTCOMPUTER	Yes
36 Configurations of the HP ProBo	ok x360 11 65 FF is I

36. Configurations of the HP ProBook x360 11 G5 EE is ENERGY STAR<sup>®</sup> qualified are identified as HP ProBook x360 11 G5 EE ENERGY STAR on HP websites and on http://www.energystar.gov.

37. Based on US EPEAT<sup>®</sup> registration according to IEEE 1680.1-2018 EPEAT<sup>®</sup>. Status varies by country. Visit http://www.epeat.net for more information.

#### DISPLAYS

**Note:** All specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

Panel LCD 11.6 HD AG WLED SVA 45% NTSC 220	Outline Dimensions (W x H x D)	278.5 x 168.5 mm (max)
nits eDP Slim	Active Area	256.125 x 144 mm
	Weight	210 g max
	Diagonal Size	11.6 (inches)
	Thickness	3.0 mm (max)
	Interface	eDP1.2
	Surface Treatment	AntiGlare
	Touch Enabled	No
	Contrast Ratio	400:1 (typical)
	Refresh Rate	60 Hz
	Brightness	220 nit typical (panel only)
	Pixel Resolution	1366 x 768 (HD)
	Format of LCD Pixel Arrangement	RGB
	Backlight	LED
	Color Gamut Coverage	45% of NTSC
	Color Depth	6 bits
	Viewing Angle	SVA 40/40/15/30

Panel LCD 11.6 HD AG			
WLED SVA 45% NTSC			
220 nits eDP Slim			

Outline Dimensions<br/>(W x H x D)278.5 x 168.5 mm (max)Active Area256.125 x 144 mmWeight210 g maxDiagonal Size11.6 (inches)



## **Technical Specifications**

Thickness	3.0 mm (max)
Interface	eDP1.2
Surface Treatment	BrightView Glass
Touch Enabled	Yes
Contrast Ratio	400:1 (typical)
Refresh Rate	60 Hz
Brightness	220 nit typical (panel only)
Pixel Resolution	1366 x 768 (HD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED
Color Gamut Coverage	45% of NTSC
Color Depth	6 bits
Viewing Angle	SVA 45/45/15/35

#### Panel LCD 11.6 inch HD AG WLED UWVA 50% NTSC 220 nits eDP slim

Outline Dimensions (W x H x D)	278.5 x 168.5 mm (max)
Active Area	256.125 x 144 mm
Weight	200 g max
Diagonal Size	11.6 (inches)
Thickness	3.2 mm max
Interface	eDP1.2
Surface Treatment	BrightView Glass
Touch Enabled	Yes
Contrast Ratio	800:1 (typical)
Refresh Rate	60 Hz
Brightness	220 nit typical (panel only)
Pixel Resolution	1366 x 768 (HD)
Format of LCD Pixel Arrangement	RGB
Backlight	LED
Color Gamut Coverage	50% of NTSC
Color Depth	6 bits
Viewing Angle	UWVA 85/85/85/85



## **Technical Specifications**

### **STORAGE AND DRIVES**

eMMC 64 GB MO-276	Drive Weight	0.2	
MMCv5.0	Height	1.4 mm	
	Width	11.5 x 13 mm	
	Interface	MMC potocal	
	Seek Time	Sequential Read	Sequential Write
		Up to 250 MB/s	Up to 70 MB/s
	Logical Blocks	32 GB(31,268,536,320 Bytes)/64 GB(62,537,072,640 Bytes)	
	Operating Temperature	0 to 70	
	Security Features	HS400	

128 GB 2280 M2 SATA-3	Form Factor	M.2 2280	
TLC Solid State Drive	Capacity	128 GB	
	NAND Type	TLC	
	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	Weight	0.02 lb (10 g)	
	Interface	ATA-8, SATA 3.0	
	Seek Time	Sequential Read	Sequential Write
		Up To 520 MB/s	Up To 450 MB/s
	Logical Blocks	250,069,680	
	Operating Temperature	32° to 158°F (0° to 70°C) [ambient temp]	
	Features	DIPM; TRIM; DEVSLP	

256 GB 2280 M2 SATA-3 TLC Solid State Drive	Form Factor	M.2 2280				
	Capacity	256 GB				
	NAND Type	TLC				
	Height	0.09 in (2.3 mm)				
	Width	0.87 in (22 mm)				
	Interface	ATA-8, SATA 3.0				
	Seek Time	Sequential Read	Sequential Write			
		Up To 540 MB/s	Up To 515 MB/s			
	Logical Blocks	500,118,192				



### **Technical Specifications**

Operating Temperature32° to 158°F (0° to 70°C) [ambient temp]FeaturesDIPM; TRIM; DEVSLP



## **Technical Specifications**

### **NETWORKING/COMMUNICATIONS**

IEI WURKING/CUMMU	NICATIONS	
Intel® 9560	Wireless LAN	IEEE 802.11a
802.11a/b/g/n/ac (2x2)	Standards	IEEE 802.11b
WiFi and Bluetooth® 5.0 Combo¹ non-vPro		IEEE 802.11g
		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi <sup>®</sup> certified
	Frequency Band	•802.11b/g/n
		2.402 – 2.482 GHz
		•802.11a/n/ac
		4.9 – 4.95 GHz (Japan)
		5.15 – 5.25 GHz
		5.25 – 5.35 GHz
		5.47 – 5.725 GHz
		5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps
		•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
		•802.11ac: MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz &
		160MHz)
	Modulation	Direct Sequence Spread Spectrum
		BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security <sup>3</sup>	<ul> <li>IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode</li> </ul>
		only
		•AES-CCMP: 128 bit in hardware
		•802.1x authentication
		•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
		•WPA2 certification
		•IEEE 802.11i
		•WAPI
	Network	Ad-hoc (Peer to Peer)
	Architecture	Infrastructure (Access Point Required)
	Models	



cations			
Roaming	IEEE 802.11 compliant	roaming between access points	
Output Power <sup>2</sup>	• 802.11b : +18.5dBm minimum		
	• 802.11g : +17.5dBm minimum		
	• 802.11a : +18.5dBm minimum		
	• 802.11n HT20(2.4GH	z) : +15.5dBm minimum	
		z) : +14.5dBm minimum	
	• 802.11n HT20(5GHz)	: +15.5dBm minimum	
	• 802.11n HT40(5GHz)	: +14.5dBm minimum	
	• 802.11ac VHT80(5GH	z) : +11.5dBm minimum	
	• 802.11ac VHT160(5G	Hz) : +11.5dBm minimum	
<b>Power Consumption</b>	•Transmit mode 2.0 W		
	•Receive mode 1.6 W		
	•Idle mode (PSP) 180 n	nW (WLAN Associated)	
	•Idle mode 50 mW (WL	AN unassociated)	
	•Connected Standby 10	)mW	
	•Radio disabled 8 mW		
Power Management	ACPI and PCI Express co	ompliant power management	
	802.11 compliant powe	er saving mode	
Receiver Sensitivity <sup>3</sup>	<sup>3</sup> 802.11b, 1Mbps: -93.5dBm maximum		
	802.11b, 11Mbps: -84c	IBm maximum	
	802.11a/g, 6Mbps: -86dBm maximum		
	802.11a/g, 54Mbps: -72dBm maximum		
	802.11n, MCS07: -67dBm maximum		
	802.11n, MCS15: -64dBm maximum		
	802.11ac, MCS0: -84dBm maximum		
	802.11ac, MCS9: -59dB	8m maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display		
	enclosure		
	Two embedded dual ba	nd 2.4/5 GHz antennas are provided to the card	
	to support WLAN MIMO	communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCa	rd with CNVi Interface	
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm		
	2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8 g		
	2. Type 126: 1.3 g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	–40° to 176° F (–40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
	Non-operating	5% to 95% (non-condensing)	



## **Technical Specifications**

ations					
Altitude	Ор	erating	0 to 10,000 ft (3,048 m)		
	No	n-operating	0 to 50,000 ft (15,240 m)		
LED Activ	v <b>ity</b> LE	D Amber – Radio OFI	F		
	LE	D White – Radio ON			
1.	Check latest softw	are/driver release f	or updates on supported security features.		
			ountry according to local regulations.		
		• •	acket error rate of 8% for 802.11b (CKK		
			acket error rate of 10% for 802.11a/g (OFDM modulation). etooth 4.0/4.1/4.2/5.0 Wireless Technology		
nP illeyia	teu module with b	Slueloolii 4.0/4.1/4	.2/5.0 Whetess Technology		
Bluetooth	Specification	4.0/4.1/4.2/5.0	Compliant		
Frequency	Band	2402 to 2480 MI	Hz		
Number of	Available Channe	<b>ls</b> Legacy: 0~79 (1	MHz/CH)		
		BLE: 0~39 (2 MH	z/CH)		
Signaling I	)ata Rate	Legacy: 3 Mbps s	signaling data rate <sup>1</sup> 2.17 Mbps		
			naling data rate <sup>1</sup> 0.2 Mbps		
		1. Actual throug	hput may vary.		
		Legacy: Synchro	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps,		
		voice			
		channels	channels		
			Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1		
		kbps			
-		-	0H5) or 864 kbps symmetric (3-EV5)		
Transmit P	ower		omponent shall operate as a Class II Bluetooth		
		device with a ma	aximum transmit power of + 4 dBm for BR and EDR.		
Power Con	sumption	Peak (Tx) 330 m	Peak (Tx) 330 mW		
		Peak (Rx) 230 m	Peak (Rx) 230 mW		
		Selective Susper	Selective Suspend 17 mW		
Bluetooth	Software Support	ed Microsoft Windo	d Microsoft Windows Bluetooth Software		
Link Topol	ogy				
Power Mar	agement	Microsoft Windo	Microsoft Windows ACPI, and USB Bus Support		
Certificati	ons	FCC (47 CFR) Par	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Mar	-	ETS 300 328, ET	ETS 300 328, ETS 300 826		
Certifications		Low Voltage Dire	Low Voltage Directive IEC950		
		UL, CSA, and CE I	Mark		
Bluetooth	Profiles Supporte	d BT4.1-ESR 5/6/7	-		
		LE Link Layer Pir	ıg		
		LE Dual Mode			
		LE Link Layer	le Directed Advertising		
			LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels		

Train Nudging & Interlaced Scan



## **Technical Specifications**

BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)



Intel® Wi-Fi 6 AX200 + Blueteeth E (802, 11 pr	Wireless LAN Standards	IEEE 802.11a
Bluetooth 5 (802.11ax 2x2, non-vPro,		IEEE 802.11b
supporting gigabit file		IEEE 802.11g
transfer speeds)		IEEE 802.11n
non-vPro		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi <sup>®</sup> certified
	Frequency Band	•802.11b/g/n/ax
		2.402 – 2.482 GHz
		•802.11a/n/ac/ax
		4.9 – 4.95 GHz (Japan)
		5.15 – 5.25 GHz
		5.25 – 5.35 GHz
		5.47 – 5.725 GHz
		5.825 – 5.850 GHz
	Data Rates	•802.11b: 1, 2, 5.5, 11 Mbps
		•802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		•802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)
		•802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, 80MHz & 160MHz)
		• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz,
		80MHz & 160MHz)
	Modulation	Direct Sequence Spread Spectrum
		OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security <sup>3</sup>	•IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g
	,	mode only
		•AES-CCMP: 128 bit in hardware
		•802.1x authentication
		•WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.
		•WPA2 certification
		•IEEE 802.11i
		•WAPI



Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power <sup>2</sup>	• 802.11b : +18.5dBm minimum	
	• 802.11g : +17.5dBm minimum	
	• 802.11a : +18.5dBm minimum	
	• 802.11n HT20(2.4GHz) : +15.5dBm minimum	
	• 802.11n HT40(2.4GHz) : +14.5dBm minimum	
	• 802.11n HT20(5GHz) : +15.5dBm minimum	
	• 802.11n HT40(5GHz) : +14.5dBm minimum	
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum	
	• 802.11ac VHT160(5GHz) : +11.5dBm minimum	
	• 802.11ax HT40(2.4GHz) : +10dBm minimum	
	• 802.11ax VHT160(5GHz) : +10dBm minimum	
Power Consumption	•Transmit mode: 2.0 W	
	•Receive mode: 1.6 W	
	<ul> <li>Idle mode (PSP) 180 mW (WLAN Associated)</li> </ul>	
	<ul> <li>Idle mode: 50 mW (WLAN unassociated)</li> </ul>	
	<ul> <li>Connected Standby/Modern Standby: 10mW</li> </ul>	
	•Radio disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management	
	802.11 compliant power saving mode	
Receiver Sensitivity <sup>3</sup>	•802.11b, 1Mbps : -93.5dBm maximum	
	•802.11b, 11Mbps : -84dBm maximum	
	• 802.11a/g, 6Mbps : -86dBm maximum	
	• 802.11a/g, 54Mbps : -72dBm maximum	
	• 802.11n, MCS07 : -67dBm maximum	
	• 802.11n, MCS15 : -64dBm maximum	
	• 802.11ac, MCS0 : -84dBm maximum	
	• 802.11ac, MCS9 : -59dBm maximum	
	•802.11ax, MCS11(HT40): -59dBm maximum	
	•802.11ax, MCS11(VHT160): -58.5dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the	
	display enclosure	
	Two embedded dual band 2.4/5 GHz antennas are provided to	
	the card to support WLAN MIMO communications and Bluetooth	
	communications	
Form Factor	PCI-Express M.2 MiniCard	
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm	
	2. Type 1216: 1.67 x 12.0 x 16.0 mm	



## **Technical Specifications**

Weight	1. Туре 2230: 2.8 g		
	2. Type 126: 1.3	g	
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	–40° to 176° F (–40° to 80° C)	
Humidity	Operating	10% to 90% (non-condensing)	
	Non-operating	5% to 95% (non-condensing)	
Altitude	Operating	0 to 10,000 ft (3,048 m)	
	Non-operating	0 to 50,000 ft (15,240 m)	
LED Activity	LED Amber – Radio OFF		
	LED OFF – Radio ON		

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Bluetooth 4.0/4.1/4.2/5.0/5.1 Wireless Technology

Bluetooth Specification	4.0/4.1/4.2/5.0/5.1 Compliant		
Frequency Band	2402 to 2480 MHz		
Number of Available Channels	Legacy: 0~79 (1 MHz/CH)		
	BLE: 0~39 (2 MHz/CH)		
Signaling Data Rate	Legacy: 3 Mbps signaling data rate <sup>1</sup> 2.17 Mbps BLE: 1 Mbps signaling data rate <sup>1</sup> 0.2 Mbps 1. Actual throughput may vary.		
	Legacy: Synchronous Connection Oriented links up to 3, 64 kbps, voice channels		
	Legacy: Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth component shall operate as a Class II Bluetooth device with a maximum transmit power of + 9.5 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW		
	Peak (Rx) 230 mW		
	Selective Suspend 17 mW		
Bluetooth Software Supported Link Topology	I Microsoft Windows Bluetooth Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249		
Power Management Certifications	ETS 300 328, ETS 300 826		



	Low Voltage Directive IEC950
	UL, CSA, and CE Mark
<b>Bluetooth Profiles Supported</b>	BT4.1-ESR 5/6/7 Compliance
	LE Link Layer Ping
	LE Dual Mode
	LE Link Layer
	LE Low Duty Cycle Directed Advertising
	LE L2CAP Connection Oriented Channels
	Train Nudging & Interlaced Scan
	BT4.2 ESR08 Compliance
	LE Secure Connection- Basic/Full
	LE Privacy 1.2 —Link Layer Privacy
	LE Privacy 1.2 – Extended Scanner Filter Policies
	LE Data Packet Length Extension
	FAX Profile (FAX)
	Basic Imaging Profile (BIP)2
	Headset Profile (HSP)
	Hands Free Profile (HFP)
	Advanced Audio Distribution Profile (A2DP)



Realtek Dual Band	Wireless LAN	IEEE 802.11a
Wireless- 8852AE	Standards	IEEE 802.11b
802.11ax (2x2) Wi-Fi 6		IEEE 802.11g
and Bluetooth® 5.2 Combo, non-vPro™¹		IEEE 802.11n
		IEEE 802.11ac
		IEEE 802.11ax
		IEEE 802.11d
		IEEE 802.11e
		IEEE 802.11h
		IEEE 802.11i
		IEEE 802.11k
		IEEE 802.11r
		IEEE 802.11v
	Interoperability	Wi-Fi certified modules
	Frequency Band	802.11b/g/n/ax
		• 2.402 – 2.482 GHz
		802.11a/n/ac/ax
		• 4.9 – 4.95 GHz (Japan)
		• 5.15 – 5.25 GHz
		• 5.25 – 5.35 GHz
		• 5.47 – 5.725 GHz
		• 5.825 – 5.850 GHz
	Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps
		• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps
		• 802.11n: max 300Mbps
		• 802.11ac : max 866.7Mbps
		• 802.11ax : max 1201Mbps
	Modulation	Direct Sequence Spread Spectrum
		BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM
	Security <sup>3</sup>	<ul> <li>IEEE and WiFi certified 64 / 128 bit WEP encryption for a/b/g mode only</li> </ul>
		AES-CCMP: 128 bit in hardware
		• 802.1x authentication
		<ul> <li>WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.</li> </ul>
		WPA2 certification
		WPA3 certification
		• IEEE 802.11i
		• WAPI
	Network	Ad-hoc (Peer to Peer)
	Architecture	Infrastructure (Access Point Required)
	Models Booming	IEEE 902 11 compliant reaming between access points
	Roaming	IEEE 802.11 compliant roaming between access points



Lations			
Output Power <sup>2</sup>	• 802.11b : +18.5dBm r	ninimum	
	• 802.11g : +17.5dBm r	ninimum	
	• 802.11a : +18.5dBm minimum		
	• 802.11n HT20(2.4GHz	z) : +15.5dBm minimum	
	• 802.11n HT40(2.4GHz	؛) : +14.5dBm minimum	
	• 802.11n HT20(5GHz)	: +15.5dBm minimum	
	• 802.11n HT40(5GHz)	: +14.5dBm minimum	
	• 802.11ac VHT80(5GH	z) : +11.5dBm minimum	
	• 802.11ax HE40(2.4GF	lz) : +10dBm minimum	
	• 802.11ax HE80(5GHz)	: +10dBm minimum	
<b>Power Consumption</b>	• Transmit mode :2.5 W	,	
	• Receive mode :2 W		
	• Idle mode (PSP) 180 n	nW (WLAN Associated)	
	• Idle mode :50 mW (WI	AN unassociated)	
	<ul> <li>Connected Standby/M</li> </ul>	odern Standby: 10mW	
	• Radio disabled: 8 mW		
Power Management	ACPI and PCI Express co	mpliant power management	
	802.11 compliant powe	er saving mode	
Receiver Sensitivity <sup>4</sup>	802.11b, 1Mbps : -93.5	dBm maximum	
	802.11b, 11Mbps : -84d	IBm maximum	
	802.11a/g, 6Mbps : -86	dBm maximum	
	802.11a/g, 54Mbps : -7	2dBm maximum	
	802.11n, MCS07 : -67dl	3m maximum	
	802.11n, MCS15 : -64dl	3m maximum	
	802.11ac, MCS0 : -84dE	3m maximum	
	802.11ac, MCS9 : -59dE	3m maximum	
	802.11ax, MCS11(HE40	): -57dBm maximum	
	802.11ax, MCS11(HE80	): -54dBm maximum	
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
	Two embedded dual ba	nd 2.4/5 GHz antennas are provided to the card	
	to support WLAN MIMO	communications and Bluetooth communications	
Form Factor	PCI-Express M.2 MiniCard		
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm		
	2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g		
	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)	
	Non-operating	–40° to 176° F (–40° to 80° C)	



### **Technical Specifications**

Humidity	Opera	ting	10% to 90% (non-condensing)
	Non-o	perating	5% to 95% (non-condensing)
Altitude	Opera	ting	0 to 10,000 ft (3,048 m)
	Non-o	perating	0 to 50,000 ft (15,240 m)
LED Activity	LED A	mber – Radio OFF	
	LED W	/hite – Radio ON	
HP Integrated Module with Bluetooth 4.0/4.1/4.2/		/5.2 Wireless Tecl	hnology
Bluetooth Specification		4.0/4.1/4.2/5.0/5	.1 Compliant/5.2 Compliant
Frequency Band		2402 to 2480 MHz	2
Number of Available Cha	annels	Legacy: 0~79 (1 M	IHz/CH)
		BLE: 0~39 (2 MHz)	/СН)
Data Rates and Through	iput	Legacy : 3 Mbps da	ata rate; throughput up to 2.17 Mbps
		BLE : 1 Mbps data	rate; throughput up to 0.2 Mbps
		Legacy : Synchron	ous Connection Oriented links up to 3, 64 kbps,
		voice channels	
		Legacy : Asynchro	nous Connection Less links 2178.1 kbps/177.1
		kbps asymmetric	(3-DH5) or 864 kbps symmetric (3-EV5)
Transmit Power		The Bluetooth cor	nponent shall operate as a Class II Bluetooth
		device with a max	imum transmit power of + 4 dBm for BR and EDR.

1. Wireless access point and internet service required and sold separately. Availability of public wireless access points limited. Wi-Fi 5 (802.11 ac) is backwards compatible with prior 802.11 specs.

2. The FCC has declared as of September 1, 2014 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels.

3. Check latest software/driver release for updates on supported security features.

4. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



## **Technical Specifications**

### POWER

HP 45 W Smart	<b>Dimensions</b> (H x W x D)	3.74 x 1.57 x 1.04 in (9.5 x	( 4.0 x 2.65 cm)
AC adapter	Weight	0.386 lb (175 g) max	
		Not including power cord.	Power cord varies by country
	Input	90 to 265 VAC	
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 to 63 Hz
		Input AC current	1.4 A at 90 VAC
	Output	Output power	45 W
		DC output	19.5 V
		Hold-up time	5ms at 115 VAC input
		Output current protection	<b>n</b> <8.0A
	Connector	4.5mm Barrel Type, 3 pin/	grounded, mates with interchangeable cords
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5000m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	Worldwide safety standar Agency approvals - C-UL-I B, CISPR22 Class B, CCC, N	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, SELV; JS, NORDICS, DENAN, EN55022 Class B, FCC Class OM-1 NYCE. rs at 25°C ambient condition.

HP 65 W EM Smart AC	Dimensions	<b>mensions</b> 102 x 55 x 30 mm	
adapter	Weight	270 g +/- 10 g	
		Not including power cord	. Power cord varies by country
	Input	Input Efficiency	87% min at 115V/230V
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 VAC and maximum load
	Output	DC output	65W(19.5V/3.33A)
		Hold-up time	5 msec at 115 VAC input
		Output current limit	<11A, Over voltage protection- 29V max automatic shutdown
	Connector	4.5mm Barrel Type, 3 pin	/grounded, mates with interchangeable cords



Technical Spec	ifications			
·	Environmental Design	Operating temperature	0° to 35° C	
		Non-operating (storage) temperature	-20° to 85° C	
			0 to 5,000 m 0% to 95%	
		Storage Humidity	0% to 95%	
	EMI and Safety Certifications	EN60950, UL60950, Class DENAN, EN55022 Class B,	Worldwide safety standards - IEC60950, 1, SELV; Agency approvals - C-UL-US, NORDICS, FCC Class B, CISPR22 Class B, CCC, NOM-1 NYCE less than 0.1% annually within the first three	
1P 45 W USB type C	Dimensions	94.0mm x 40.0mm x 26.5	5 mm	
Straight 1.8 m	Weight	192.5 g +/-10%		
AC Adapter		Not including power cord. Power cord varies by country		
	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V: 81.5% 9V: 86.7% 12V: 87.41% 15V: 87.8%	
		Input frequency range	47 ~ 63Hz	
		Input AC current	Max. 1.4 A at 90 Vac	
	Output	Output power	5V/15W 9V/27W 12V/36W 15V/45W	
		DC output	5V/9V/12V/15V	
		Hold-up time	5ms at 115 Vac input	
		Output current limit	<5.0A	
	Connector	USB Type-C		
	Environmental Design	Operating temperature	32°F to 95° F (0° to 35° C)	
		temperature	4°F to 185° F (-20° to 85° C)	
		Altitude	0 to 16,400 ft (0 to 5000m)	



20% to 95%

Humidity

## Technical Specifications

	EMI and Safety Certifications	Storage Humidity10% to 95%CE Mark - full compliance with LVD and EMC directivesWorldwide safety standards - IEC60950, EN60950, UL60950, Class1, SELV;Agency approvals - C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC ClassB, CISPR22 Class B, CCC, NOM-1 NYCE.MTBF - over 200,000 hours at 25°C ambient condition.	
HP 3-cell Long Life Li- Ion (48 WHr)	Dimensions (H x W x L) Weight	7.3 x 94 x 184.47 mm (0.287 x 3.7 x 7.263 inch) 0.215 kg	
	Cells/Type	3cell Lithium-Ion Prismatic cell / 596080 3cell Lithium-Ion Polymer cell / 606072	
	Voltage	11.4 V	
	Amp-hour capacity	4.212Ah	
	Watt-hour capacity	48Wh	
	Operating (Charging)	32° to 113° F (0° to 45° C)	
	Operating (Discharging)	14° to 122° F (-10° to 60° C)	
	Optional Travel Battery Available	Νο	

### **COUNTRY OF ORIGIN**

China



### Options and Accessories (sold separately and availability may vary by country)

Туре	Description	Part Number
Cases	HP Essential Top Load Case (up to 15.6")	H2W17AA
	HP Essential Backpack (up to 15.6")	H1D24AA
	HP Slim Ultrabook Top Load (up to 15.6" x .88"/22/5mm)	F3W15AA
	HP Slim Ultrabook Backpack (up to 15.6" x .88"/22/5mm)	F3W16AA
	HP Black 11.6 Always On Case	2MY57AA
	HP Slim Ultrabook Messenger	F3W14AA
Docking	HP USB-C/A universal Dock G2	5TW13AA
Input/Output	HP Comfort Grip Wireless Mouse	H2L63AA
	HP Slim USB Keyboard & Mouse Bundle	ТбТ8ЗАА
	HP 3-Button Laser Mouse	H4B81AA
	HP USB Premium Mouse	1JR32AA
	HP Wireless Premium Mouse	1JR31AA
	HP Essential USB Mouse	2TX37AA
	HP USB Travel Mouse	G1K28AA
	HP Slim Bluetooth Mouse	F3J92AA
	HP Slim Wireless keyboard and mouse	T6L04AA
	HP USB-C to USB 3.0 Adapter	N2Z63AA
	HP USB-C to 3 and 4.5mm Adapter	N2Z65AA
	HP HDMI to VGA Adapter	H4F02AA
	HP USB-C to RJ45 Adapter	V7W66AA
	HP Pro Pen with Spare Tips	TBD
	HP Pro Pen Nib Set	TBD
Power	HP 45W Smart AC Adapter (4.5mm)	H6Y88AA
	HP 65W Smart AC Adapter (4.5mm)	H6Y89AA
	HP 45W LC USB-C Power Adapter	1MZ01AA
	HP Notebook Powerbank	N9F71AA
	HP USB-C ESSENTIAL POWER BANK	3TB55AA
	HP USB-C Notebook Power Bank	2NA10AA
Storage	HP External USB Optical Drive	F2B56AA
Security	HP Nano Keyed Cable Lock	1AJ39AA
UCC	HP Stereo USB Headset	T1A67AA
	HP Stereo 3.5mm Headset	T1A66AA



## Options and Accessories (sold separately and availability may vary by country)

\*Supported using the USB connection for video and data. Power is not supported and must be provided directly to the Notebook with the power adapter that comes with the unit



### Summary of Changes

Date of change:	Version History:		Description of change:
February 28, 2020	V1 to V2	Added	Environmental Section
May 13, 2020	V2 to V3	Updated	Military Standards information and removed old docking stations.
June 25, 2020	V3 to V4	Updated	HDMI port
July 07, 2020	V4 to V5	Updated	Accessories section
September 17, 2020	V5 to V6	Removed	HP USB-C/A universal Dock G2
March 4, 2021	V6 to V7	Added	Speaker Power Section
April 20, 2021	V7 to V8	Updated	Input/ Output Section Updated
July 19, 2021	V8 to V9	Added	Display Section Updated
August 9, 2021	V9 to V10	Added	WLAN in Networking/Communications section

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